



Radio Wireless Week

20-23 January 2019, Orlando, FL, USA

Paper Deadline
July 24, 2018



IEEE



<http://www.radiowirelessweek.org/>

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Call For Papers

The 2019 IEEE Radio and Wireless Symposium (RWS2019) will be held during the week of 20 January 2019 in Orlando, FL, USA.



RWS2019 and the 19th IEEE Topical Meeting on Silicon Monolithic Integrated Circuits SiRF2019 are co-located and will continue to hold joint sessions. Topical conferences held in parallel provide more focused sessions in the areas of RF Power Amplifiers (PAWR), Wireless Sensors and Sensor Networks (WiSNet), and The Topical Workshop on the Internet of Space (TWIOS). The RWS Demonstration Track provides an interactive forum for hands-on demonstration of latest wireless experiments and innovations. There are also Focus sessions on 5G and MM-Wave to THz Technologies and Applications.

RWS Papers featuring innovative work are solicited in (but not limited to) the following areas:

1. High-speed and Broadband Wireless Technologies

- Broadband Fixed Wireless and Last-Mile Access
- Ultra-High Data Rate Communications Links - Powerline Communication Technologies
- 3G/4G/5G Wireless Communication Services
- Ultra-Wideband (UWB) Systems
- Optical Networks and Systems

2. Emerging Wireless Technologies and Applications

- M2M & V2V Technologies & Applications
- Resource Management, Security
- Femtocell and Heterogeneous Networks
- Green, Sustainable Wireless Tech. & Networks

3. Wireless System Architecture and Modeling

- Ad Hoc Network Techniques for Internetworking
- Distributed Network Architectures and Systems
- Wireless Mesh and Broadband Local/Personal/ Body Area Networks
- Wireless Security and RFID Technologies

4. Propagation/Channel Modeling and Utilization

- Propagation/Channel Characterization & Modeling - Fading Countermeasures
- Spectrum Sensing Technologies
- Frequency and Channel Allocation Algorithms

5. Digital Signal Processing, SDR, & Cognitive Radio

- Digital/Analog Adaptive/Collaborative Signal Processing
- Methods for Signal Integrity and Signal Conditioning
- Interference Mitigation and Cancellation Techniques
- Software/Hardware architectures, Algorithms
- MAC, Networking protocols, Policies, Standardization
- Dynamic Spectrum Sharing, Coexistence, Interoperability

6. Applications to Bio-Medical, Environmental, and Internet of Things

- Miniaturization and Integration of Wireless Technologies
- Personal Area Networks and Body area Sensor Networks
- Wireless Positioning Technologies & Remote Sensing

7. MIMO and Multi-Antenna Communications

- MIMO, MU-MIMO, Space-Time Processing - Relaying Technologies
- Cooperative/Collaborative Technology
- Multi-Beam Smart Antennas

8. Antenna Technologies

- Passive & Active Antennas from RF to THz Frequencies
- Miniaturized, Multi-frequency and Broadband Antennas
- Wireless Platform Integrated Antennas

9. Transceiver & Front-end Technologies, SOC & SiP

- Receiver, Transmitter and Transceiver Components - Active Circuits and Sub-Systems
- Multi-Standard Circuits and Sub-systems
- Low-Power/Low Noise RF/Analog IC and SoC
- Highly Integrated Transceivers for Sensing and Imaging

10. Passive Components & Packaging

- Discrete, Embedded and Distributed Passive Components, Filters, Couplers and Signal Separation Devices
- Discrete and Highly Integrated Packaging
- 3D-Packaging, Interconnects, and Applications
- Packaging of MEMs, Biosensors, Organic ICs, etc.

11. MM-Wave to THz Technology & Applications

- Device and Circuit Concept & Demonstration
- Unique Receivers and Transmitters - Integrated Circuits
- Wireless Links, Arrays & Applications

12. 3D & Novel Engineered Materials

- Additive 3D manufacturing for wireless applications
- Novel Engineered Materials for Antenna, Packaging, Passive Devices and Flexible Electronic Integration

RWS 2019 Chair

Rashaunda Henderson, *Univ. Texas, Dallas*

RWS 2019 Co-Chair

Robert Caverly, *Villanova University*

Paper submission instructions will be found at <http://www.radiowirelessweek.org/>.

Submissions should be formatted according to the submission review. Authors should indicate preference for oral or poster presentation. All submissions must be received by **24 July 2018**.

All accepted papers will be published in a digest and be included in IEEE Xplore Digital Library. Submissions will be evaluated based on novelty, significance of the work, technical content, interest to the audience, and presentation.